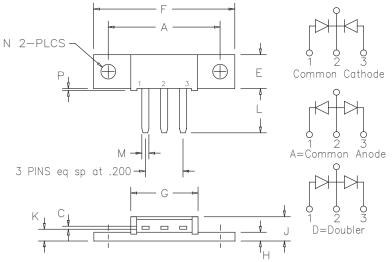
Schottky MiniMod FST8130 — FST8145



	Dim.	Dim. Inches		Millimeter	
		Minimum	Maximum	Minimum	Maximum Notes
ĺ	Α	1.180	1.195	29.97	30.35
	С	.027	.037	0.69	0.94
	Ε	.350	.370	8.89	9.40
	F	1.490	1.510	37.85	38.35
	G	.695	.715	17.65	18.16
	Н	.088	.098	2.24	2.49
	J	.240	.260	6.10	6.60
	K	.115	.135	2.92	3.43
	L	.460	.480	11.68	12.19
	М	.065	.085	1.65	2.16
	Ν	.151	.161	3.84	4.09 Dia.
	Р	.015	.025	0.38	0.64

Note: Baseplate Common with Pin 2

	,		
Microsemi Catalog Numb	Industry per Part Number	Working Peak Reverse Voltage	Repetitive Peak Reverse Voltage
FST8130*		30V	30V
FST8135*	80CNQ035, A 84CNQ035	35V	35V
FST8140*	80CNQ040, A 84CNQ040	40V	40V
FST8145*	80CNQ045, A 84CNQ045	45V	45V
*Add	the Suffix A for Com	nmon Anode, D f	or Doubler

- Schottky Barrier Rectifier
- Guard Ring Protection
- Common Cathode Center Tap
- 2X40 Amperes avg.
- 150°C Junction Temperature
- Reverse Energy Tested
- Low Forward Voltage
- ROHS Compliant

Electrical Characteristics

Average forward current per pkg
Average forward current per leg
Maximum surge current per leg
Max repetitive peak reverse current per leg
Max peak forward voltage per leg
Max peak forward voltage per leg
Max peak reverse current per leg
Max peak reverse current per leg
Typical junction capacitance per leg

| F(AV) 80 Amps | F(AV) 40 Amps | FSM 800 Amps | R(OV) 2 Amps | VFM 0.47 Volts | VFM 0.53 Volts | RM 500 mA | RM 3.0 mA | CJ 2100 pF TC = 110°C, Square wave, ReJC = 0.5°C/W TC = 110°C, Square wave, ReJC = 1.0°C/W 8.3 ms, half sine, TJ = 150°C f = 1 KHZ, 25°C, 1 usec square wave FM = 40A: TJ = 150°C* FM = 40A: TJ = 25°C* VRRM, TJ = 125°C* VRRM, TJ = 25°C VR = 5.0V, TC = 25°C

*Pulse test: Pulse width 300 µsec, Duty cycle 2%

Thermal and Mechanical Characteristics TSTG Storage temp range -55°C to 175°C TJ Operating junction temp range -55°C to 150°C 1.0°C/W Rejc Max thermal resistance per leg Junction to case 0.5°C/W Max thermal resistance per pkg ROJC Junction to case 0.3°C/W Typical thermal resistance (greased) Case to sink Mounting Base Torque 10 inch pounds maximum Weight 0.3 ounce (8.4 grams) typical



FST8130 - FST8145

Figure 1 Typical Forward Characteristics — Per Leg

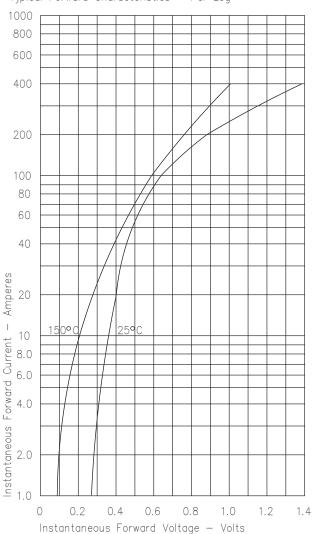


Figure 2
Typical Reverse Characteristics — Per Leg

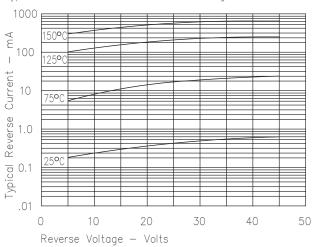


Figure 3 Typical Junction Capacitance — Per Leg

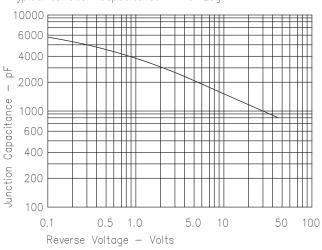


Figure 4
Forward Current Derating — Per Leg

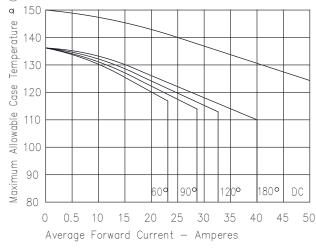
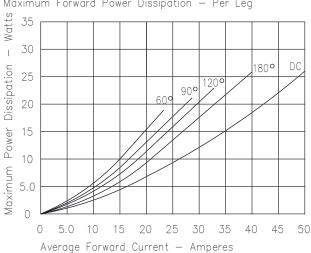


Figure 5
Maximum Forward Power Dissipation — Per Leg





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